

C0603C335M9PAC7411

SMD Comm X5R, Ceramic, 3.3 uF, 20%, 6.3 VDC, X5R, SMD, MLCC, Temperature Stable, Class II, 0603



Click here for the 3D model.

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.10mm
S	0.7mm MIN
В	0.35mm +/-0.15mm

Packaging Specifications		
Packaging	T&R, 330mm, Paper Tape	
Packaging Quantity	15000	

General Information	
Series	SMD Comm X5R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	6.5 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	3.3 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	20%
Voltage DC	6.3 VDC
Dielectric Withstanding Voltage	15.75 VDC
Temperature Range	-55/+85°C
Temperature Coefficient	X5R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 0.5Vrms
Dissipation Factor	10% 1 kHz 1.0Vrms
Aging Rate	5% Loss/Decade Hour: Referee Time is 48 Hours
Insulation Resistance	30.3 MOhms

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